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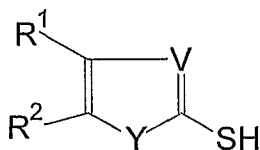
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(54) Title: NOVEL PHOTSENSITIVE RESIN COMPOSITIONS



(VI)

(57) Abstract: A photosensitive resin composition comprising: (a) at least one polybenzoxazole precursor polymer; (b) at least one compound having Structure VI wherein, V is CH or N, Y is O or NR³ wherein R³ is H, CH₃ or C₂H₅, R¹ and R² each independently are H, C₁ - C₄

alkyl group, C₁ - C₄ alkoxy group, cyclopentyl or cyclohexyl, or alternatively, R¹ and R² can be fused to produce a substituted or unsubstituted benzene ring; and (c) at least one solvent; wherein the amount of the compound of Structure VI present in the composition is effective to inhibit residue from forming when the composition is coated on a substrate and the coated substrate is subsequently processed to form an image on the substrate, and with the proviso that if the polybenzoxazole precursor polymer solely consists of polybenzoxazole precursor polymers that do not contain a photoactive moiety in the polymer, then (d) at least one photoactive compound is also present in the composition.. The present invention also concerns a process for forming a relief pattern and electronic parts using the composition.